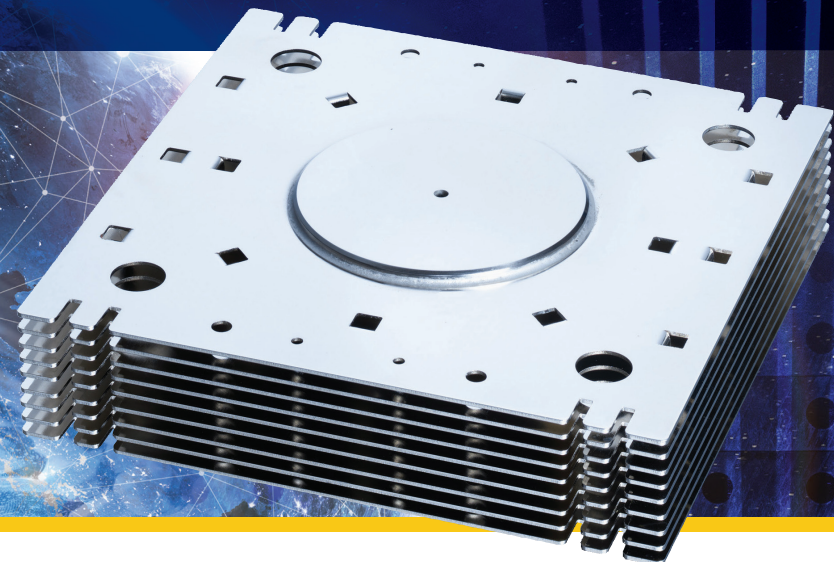


AIR COOLING

Series SKL-SF



Application

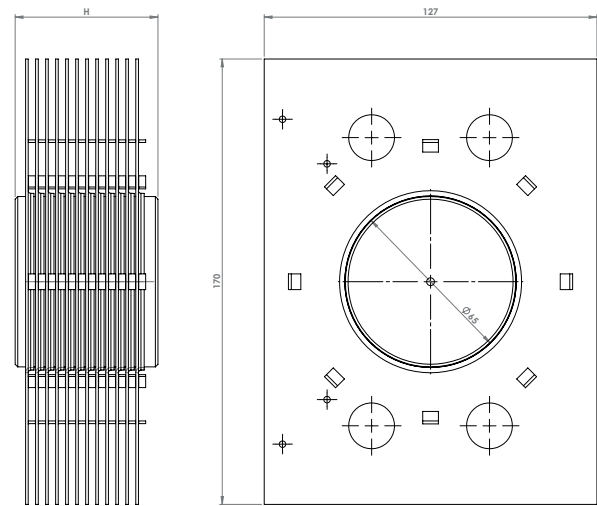
Special Heat Sink for efficient air cooling of Press Pack Disc Semi-conductors like Diode, Thyristor, GTO and IGCT Modules.

General Characteristics

Nickel plated copper heat sink for efficient air cooling of Press Pack Disc Semiconductor. This special type of heat sink is designed for high clamping forces which are required in pressed pack applications.

Type	Height H mm	Number of Fins
SKL SF-127-170-T1	13,5	3
SKL 116- L-45	27	6
SKL 152- L-75	40,5	9
SKL 201- L-105	54	12

Drawings



SKL SF-127-170-T4

